

Form PTO-1595 (Rev. 07/05)
OMB No. 0651-0027 (exp. 6/30/2008)

U.S. DEPARTMENT OF COMMERCE
United States Patent and Trademark Office

RECORDATION FORM COVER SHEET PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)

Advanced Micro Devices, Inc.

2. Name and address of receiving party(ies)

Name: Vantis Corporation

Internal Address: _____

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) 6/15/1999

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Joint Research Agreement

☐ Government Interest Assignment

☐ Executive Order 9424, Confirmatory License

☐ Other _____

Street Address: 995 Stewart Drive

City: Sunnyvale

State: CA

Country: USA Zip: 94088

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application or patent number(s):

☐ This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

6455912

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Mark L Becker

Internal Address: Lattice Semiconductor Corporation

Street Address: 5555 NE Moore Ct

City: Hillsboro

State: OR Zip: 97124

Phone Number: 503-268-8629

Fax Number: 503-268-8077

Email Address: mark.becker@latticesemi.com

6. Total number of applications and patents involved: One

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40

☐ Authorized to be charged by credit card

☒ Authorized to be charged to deposit account

☐ Enclosed

☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____

Expiration Date _____

b. Deposit Account Number 501958

Authorized User Name Mark L Becker

9. Signature:



Signature

4/14/06
Date

Mark L Becker

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 5

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O. Box 1450, Alexandria, V.A. 22313-1450

CH \$40.00 501958 6455912

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PATENT
REEL: 017480 FRAME: 0583

ASSIGNMENT OF PATENTS, APPLICATIONS, AND INVENTIONS

WHEREAS, ADVANCED MICRO DEVICES, INC., a corporation organized and existing under the laws of the State of Delaware and having a principal place of business at One AMD Place, Sunnyvale, California, 94088 (hereinafter "ASSIGNOR"), is the owner of all right, title and interest in the Letters Patents identified in Exhibit A.

WHEREAS, PATENT PROPERTY shall include each and all of the following:

(a) the Letters Patents identified in Exhibit A and applications therefor and the inventions disclosed therein, and all embodiments of such inventions heretofore assigned to ASSIGNOR [all collectively hereinafter termed "said inventions"];

(b) all rights to apply in any and all countries of the world for patents, certificates of invention or other governmental grants on said inventions, including the right to apply for patents pursuant to the International Convention for the Protection of Industrial Property or pursuant to any other convention, treaty, agreement or understanding;

(c) any and all applications filed and any and all patents, certificates of invention or other governmental grants granted on said inventions in the United States or any other country, including each and every application filed and each and every patent granted on any application which is a division, substitution, or continuation of any of said applications;

(d) each and every reissue or extension of any of said patents;

(e) each and every patent claim resulting from a reexamination certificate for any and all of said patents;

(f) the unrestricted, worldwide right to sue for and all claims for damages, profits or other recovery resulting from infringement, including past infringement, of any of the foregoing;

- (g) the unrestricted, worldwide right to license the property identified in (a) through (f) above without the consent of and without accounting to the ASSIGNOR defined above;
- (h) the unrestricted, worldwide right to assign the property identified in (a) through (f) above without the consent of and without accounting to the ASSIGNOR defined above; and
- (i) each and every other right of ASSIGNOR in any of said patents prior to this Assignment.

WHEREAS, VANTIS CORPORATION, a corporation organized and existing under the laws of the State of Delaware and having a principal place of business at 995 Stewart Drive, Sunnyvale, California 94088 (hereinafter "ASSIGNEE") is to acquire from ASSIGNOR the entire right, title and interest in and to said PATENT PROPERTY.

NOW THEREFORE, for good and valuable consideration acknowledged by said ASSIGNOR to have been received in full from said ASSIGNEE:

1. ASSIGNOR hereby sells, assigns, transfers and otherwise conveys to ASSIGNEE, and ASSIGNEE's successors, legal representatives and assigns, the entire right, title and interest in and to the PATENT PROPERTY.
2. ASSIGNOR hereby authorizes and requests all patent offices with which it has made applications with respect to the Letters Patents listed on Exhibit A, including, but not limited to, the United States Patent and Trademark Office (for patent applications in the United States and those pursuant to the Patent Cooperation Treaty), the European Patent Office, the Japan Patent Office and the Korean Industrial Property Office, to issue in the name of ASSIGNEE all patents granted on applications with respect to the Letters Patents assigned to ASSIGNEE in accordance with the terms of this Assignment.

3. ASSIGNOR is the sole owner of the patents, free and clear of any liens, encumbrances or claims of any nature, and has made no agreement with respect to the patents that is inconsistent with this Assignment; however, ASSIGNEE acknowledges that the PATENT PROPERTIES will be subject to the Patent Cross License Agreement dated as of April 21, 1999 by and between ASSIGNOR, ASSIGNEE and Lattice Semiconductor Corporation.

3. ASSIGNOR further agrees to execute and cause to be executed such additional instruments as may be necessary or desirable to confirm the transfer of rights as herein contemplated and to record the transfer of rights in the United States and throughout the world.

IN WITNESS WHEREOF, ASSIGNOR has caused this instrument to be executed by its duly authorized corporate officer and delivered to ASSIGNEE this 15th day of June, 1999, in the State of California.

ADVANCED MICRO DEVICES, INC.

By: *[Signature]*

Name: Richard Previte

Title: Chairman

State of California

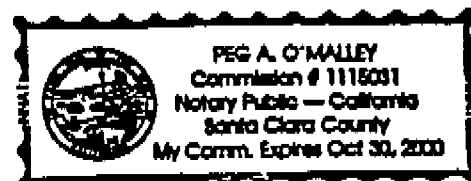
County of Santa Clara

On June 15, 1999 before me, Peg A. O'Malley, Notary Public
(name and title of officer)

personally appeared Richard Previte, Chairman, personally known to me (or proved to me on the basis of satisfactory evidence) to be the person(s) whose name(s) is/are subscribed to the within instrument and acknowledged to me that ~~he/she/they~~ executed the same in ~~his/her/their~~ authorized capacity(ies); and that by ~~his/her/their~~ signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

WITNESS my hand and official seal.

Signature: *Peg A. O'Malley*



Title	Status	Docket	Nation	App. No.	App. Date	Pat. No.	Grant Date	Division
ELECTROLYSIS DISCHARGE (ESD) PROTECTION FOR MNOS PULL UP TRANSISTORS OF A 6.0 VOLT COMPATIBLE OUTPUT BUFFER USING 2.5 VOLT PROCESS TRANSISTORS	Filed	D069	United States	09/114,717	7/13/98			WANT
A STACK TUNNELING DIELECTRIC TECHNOLOGY FOR IMPROVING DATA RETENTION OF EEPROM CELL	Filed	D098	United States	09/086,437	5/28/98			WANT
A NEW STACK TUNNELING DIELECTRIC FOR FASTER PROGRAM/ERASE SPEED AND PERIPHERAL LOGIC SPEED USED IN SINGLE POLY EEPROM BASED PROGRAMMABLE LOGIC TECHNOLOGY	Filed	D102	United States	09/086,477	6/12/98			WANT
SEMICONDUCTOR DIE ADAPTED TO ACCOMMODATE BOTH WIRE BONDING AND FLIP CHIP THERMAL REFLOW BONDING	Filed	D136	United States	09/238,052	1/27/98			WANT
WANTS VLSI FIELD PROGRAMMABLE GATE ARRAY	Inactive	D141	United States	09/071,614	1/18/98			WANT
PHOTOGRAPHIC PROCESSING USING A LATENT ALIGNMENT MARK	Filed	D142	United States	09/123,228	7/27/98			WANT
PROCESS FOR MANUFACTURING SHALLOW TRENCHES FILLED WITH DIELECTRIC MATERIAL HAVING LOW MECHANICAL STRESS	Filed	D255	United States	09/240,580	1/28/98			WANT
AN EEPROM CELL WITH SELF-ALIGNED TUNNELING WINDOW	Filed	D257	United States	09/169,492	10/6/98			WANT
BALLAST RESISTORS WITH PARALLEL STACKED MNOS TRANSISTORS USED TO PREVENT SECONDARY BREAKDOWN DURING ESD WITH 2.5 VOLT PROCESS TRANSISTORS	Filed	D334	United States	09/114,716	7/13/98			WANT
A VOLTAGE CLAMPING CIRCUIT FOR SETTING A MAXIMUM PAD VOLTAGE DURING AN ELECTROSTATIC DISCHARGE (ESD) EVENT TO PREVENT DAMAGE TO 2.5 VOLT PROCESS TRANSISTORS	Filed	D335	United States	09/114,719	7/13/98			WANT
ERASE OXIDE THICKNESS DIFFERENTIAL ON A SAME WATER FOR IMPROVING EEPROM CELL DATA RETENTION	Filed	D336	United States	09/105,246	10/1/98			WANT
OPTIMIZATION OF S/D ANNEALING TO MINIMIZE RANDOM S/D SHORTS IN MEMORY ARRAY	Filed	D356	United States	09/192,094	11/13/98			WANT
REDUCTION OF MECHANICAL STRESS IN SHALLOW TRENCH ISOLATION PROCESS	Filed	D357	United States	09/192,096	11/13/98			WANT
RAPID THERMAL CVD DEPOSITED SILICON NITRIDE FILMS TO ELIMINATE HIGH TEMPERATURE CHARGE LOSS	Filed	D484	United States	09/256,748	2/26/99			WANT
TRIPLE-OXIDE MICROELECTRONIC STRUCTURE AND FABRICATION PROCESS	Filed	D808	United States	09/232,061	1/15/99			WANT
SEMICONDUCTOR DEVICE HAVING HIGH RELIABILITY PASSIVATION AND FABRICATION METHOD	Filed	D808	United States	09/200,395	11/24/98			WANT